In the Claims:

1. A method of dissipating heat in an electrically active interconnect line in an integrated circuit comprises the steps of :

providing an electrically inactive conductor and

connecting said an electrically inactive conductor to said electrically active interconnect line as an extensions of said electrically active interconnect line to dissipate heat therefrom.

2. The method of claim 1 wherein said electrically inactive conductor is on a heat dissipating layer of a dielectric region closer to a heat dissipating substrate than said electrically active interconnect line.

3. The method of Claim 2 wherein said electrically inactive conductor is connected to said electrically active interconnect line using one or more vias through one or more heat dissipating layers.

4. The method of Claim 3 wherein said electrically inactive conductor is connected to said electrically active interconnect line using at least two vias and a conducting pad through two or more heat dissipating layers.

5. The method of Claim 2 wherein said dielectric region includes dummy metal structures and said electrically inactive conductor is aligned with one or more of said dummy metal structures to aid in dissipating heat from said electrically inactive conductor

6. The method of Claim 5 wherein said dummy metal structures is said dielectric region is between said electrically inactive conductor and said substrate.

7. The method of Claim 2 including the step of coupling said heat dissipating substrate to a heat sink.

8. The method of Claim 2 including the step of connecting said electrically inactive conductor directly to a heat sink by a via through said dielectric region.

9. The method of Claim 1 wherein said electrically inactive conductor is in a straight line.

10. The method of Claim 1 wherein said electrically inactive conductor is in not in a straight line.

11. The method of Claim 10 wherein said electrically inactive conductor is in the shape of an H with two parallel conductors and a cross connector connected to the electrically active connector.

12. The method of Claim 11 wherein said electrically inactive conductor is in the heat dissipating layer adjacent to said electrically active conductor and closer to said substrate and wherein said electrically inactive conductor and the via connection to the electrically inactive conductor is formed by the damascene process.

13. An integrated circuit, comprising:

an electrically active interconnect line within a dielectric layer having a top and bottom surface, the bottom surface of the dielectric layer being coupled to the top surface of a substrate underlying the dielectric layer; said dielectric layer having horizontally arranged heat dissipating heat dissipating layers and

an electrically inactive conductor within said dielectric layer at a heat dissipating layer closer to the substrate than said active interconnect line; said electrically inactive conductor coupled to said electrically active interconnect line as an extensions of electrically active interconnect line to dissipate heat therefrom.

14. The integrated circuit of Claim 13 wherein said electrically inactive conductor is connected to said electrically active interconnect line using one or more vias through one or more heat dissipating layers.

15. The integrated circuit of Claim 14 wherein said electrically inactive conductor is connected to said electrically active interconnect line using at least two vias and a conducting pad through two or more heat dissipating layers.

16. The integrated circuit of Claim 14 wherein said dielectric region includes dummy metal structures and said electrically inactive conductor is aligned with one or more of said dummy metal structures to aid in dissipating heat from said electrically inactive conductor

17. The integrated circuit of Claim 16 wherein said dummy metal structures is said dielectric region is between said electrically inactive conductor and said substrate.

18. The integrated circuit of Claim 13 including means for coupling said heat dissipating substrate to a heat sink.

19. The integrated circuit of claim 13 including means for connecting said electrically inactive conductor directly to a heat sink by a via through said dielectric region.

20. The integrated circuit of claim 13 including means for connecting said electrically inactive conductor directly to a heat sink by a via through said dielectric region and said substrate.